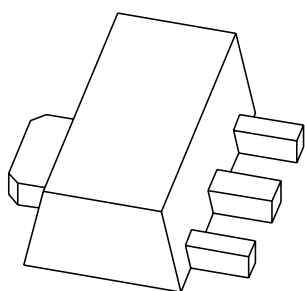


# DATA SHEET



**PBSS4350X**

**50 V, 3 A**

**NPN low  $V_{CEsat}$  (BISS) transistor**

Product specification  
Supersedes data of 2003 Nov 21

2004 Nov 04

50 V, 3 A  
NPN low  $V_{CEsat}$  (BISS) transistor

PBSS4350X

FEATURES

- SOT89 (SC-62) package
- Low collector-emitter saturation voltage  $V_{CEsat}$
- High collector current capability:  $I_C$  and  $I_{CM}$
- Higher efficiency leading to less heat generation
- Reduced printed-circuit board requirements.

APPLICATIONS

- Power management
  - DC/DC converters
  - Supply line switching
  - Battery charger
  - LCD backlighting.
- Peripheral drivers
  - Driver in low supply voltage applications (e.g. lamps and LEDs).
  - Inductive load driver (e.g. relays, buzzers and motors).

DESCRIPTION

NPN low  $V_{CEsat}$  transistor in a SOT89 plastic package.  
PNP complement: PBSS5350X.

MARKING

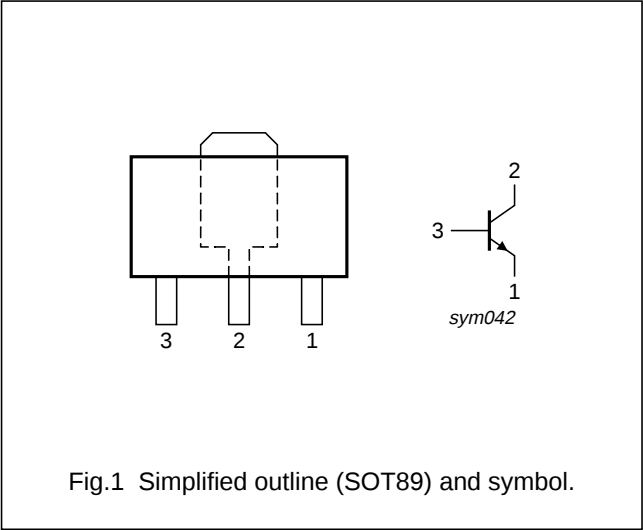
| TYPE NUMBER | MARKING CODE |
|-------------|--------------|
| PBSS4350X   | S43          |

QUICK REFERENCE DATA

| SYMBOL      | PARAMETER                 | MAX. | UNIT       |
|-------------|---------------------------|------|------------|
| $V_{CEO}$   | collector-emitter voltage | 50   | V          |
| $I_C$       | collector current (DC)    | 3    | A          |
| $I_{CM}$    | peak collector current    | 5    | A          |
| $R_{CEsat}$ | equivalent on-resistance  | 130  | m $\Omega$ |

PINNING

| PIN | DESCRIPTION |
|-----|-------------|
| 1   | emitter     |
| 2   | collector   |
| 3   | base        |



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**ORDERING INFORMATION**

| TYPE NUMBER | PACKAGE |                                                                                |         |
|-------------|---------|--------------------------------------------------------------------------------|---------|
|             | NAME    | DESCRIPTION                                                                    | VERSION |
| PBSS4350X   | SC-62   | plastic surface mounted package; collector pad for good heat transfer; 3 leads | SOT89   |

**LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

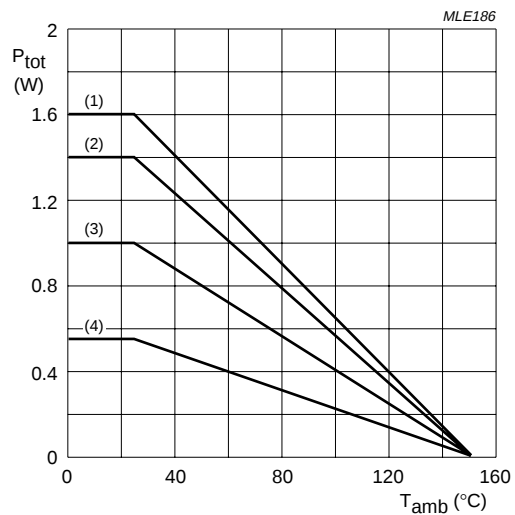
| SYMBOL    | PARAMETER                 | CONDITIONS                  | MIN. | MAX. | UNIT |
|-----------|---------------------------|-----------------------------|------|------|------|
| $V_{CBO}$ | collector-base voltage    | open emitter                | –    | 50   | V    |
| $V_{CEO}$ | collector-emitter voltage | open base                   | –    | 50   | V    |
| $V_{EBO}$ | emitter-base voltage      | open collector              | –    | 5    | V    |
| $I_C$     | collector current (DC)    | note 4                      | –    | 3    | A    |
| $I_{CM}$  | peak collector current    | limited by $T_{j(max)}$     | –    | 5    | A    |
| $I_B$     | base current (DC)         |                             | –    | 0.5  | A    |
| $P_{tot}$ | total power dissipation   | $T_{amb} \leq 25\text{ °C}$ |      |      |      |
|           |                           | note 1                      | –    | 550  | mW   |
|           |                           | note 2                      | –    | 1    | W    |
|           |                           | note 3                      | –    | 1.4  | W    |
|           |                           | note 4                      | –    | 1.6  | W    |
| $T_{stg}$ | storage temperature       |                             | –65  | +150 | °C   |
| $T_j$     | junction temperature      |                             | –    | 150  | °C   |
| $T_{amb}$ | ambient temperature       |                             | –65  | +150 | °C   |

**Notes**

1. Device mounted on a FR4 printed-circuit board; single-sided copper; tin-plated; standard footprint.
2. Device mounted on a FR4 printed-circuit board; single-sided copper; tin-plated; mounting pad for collector 1 cm<sup>2</sup>.
3. Device mounted on a FR4 printed-circuit board; single-sided copper; tin-plated; mounting pad for collector 6 cm<sup>2</sup>.
4. Device mounted on a ceramic printed-circuit board 7 cm<sup>2</sup>, single-sided copper, tin-plated.

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- (1) Ceramic PCB; 7 cm<sup>2</sup> mounting pad for collector.      (3) FR4 PCB; 1 cm<sup>2</sup> copper mounting pad for collector.  
(2) FR4 PCB; 6 cm<sup>2</sup> copper mounting pad for collector.      (4) Standard footprint.

Fig.2 Power derating curves.

50 V, 3 A

NPN low  $V_{CEsat}$  (BISS) transistor

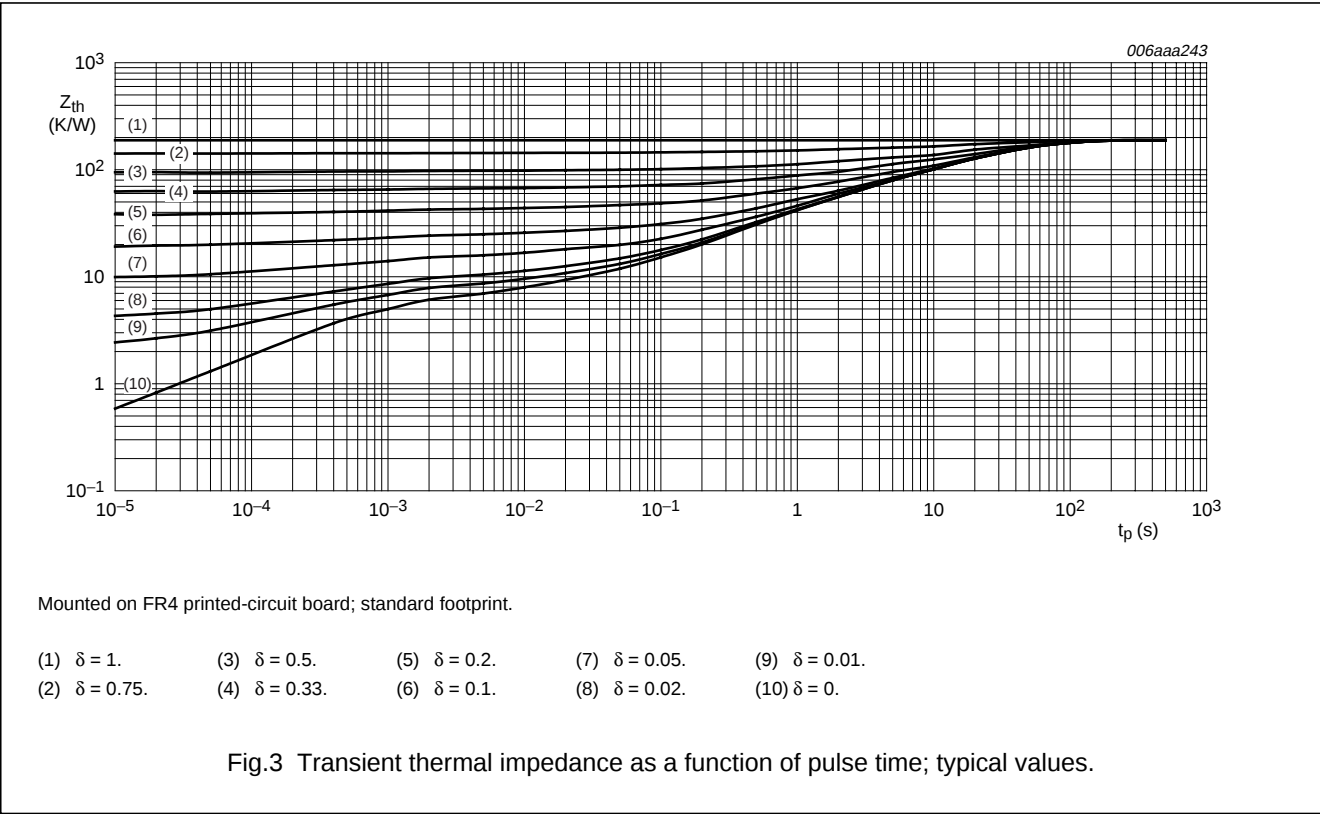
PBSS4350X

THERMAL CHARACTERISTICS

| SYMBOL        | PARAMETER                                           | CONDITIONS  | VALUE | UNIT |
|---------------|-----------------------------------------------------|-------------|-------|------|
| $R_{th(j-a)}$ | thermal resistance from junction to ambient         | in free air |       |      |
|               |                                                     | note 1      | 225   | K/W  |
|               |                                                     | note 2      | 125   | K/W  |
|               |                                                     | note 3      | 90    | K/W  |
|               |                                                     | note 4      | 80    | K/W  |
| $R_{th(j-s)}$ | thermal resistance from junction to soldering point |             | 16    | K/W  |

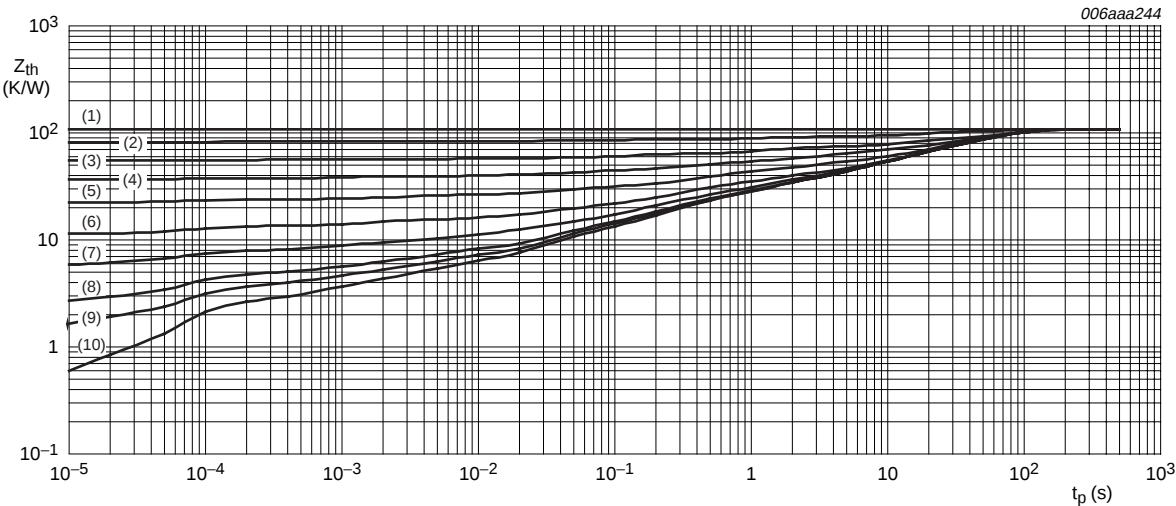
Notes

1. Device mounted on a FR4 printed-circuit board; single-sided copper; tin-plated; standard footprint.
2. Device mounted on a FR4 printed-circuit board; single-sided copper; tin-plated; mounting pad for collector 1 cm<sup>2</sup>.
3. Device mounted on a FR4 printed-circuit board; single-sided copper; tin-plated; mounting pad for collector 6 cm<sup>2</sup>.
4. Device mounted on a ceramic printed-circuit board 7 cm<sup>2</sup>, single-sided copper, tin-plated.



50 V, 3 A  
NPN low  $V_{CEsat}$  (BISS) transistor

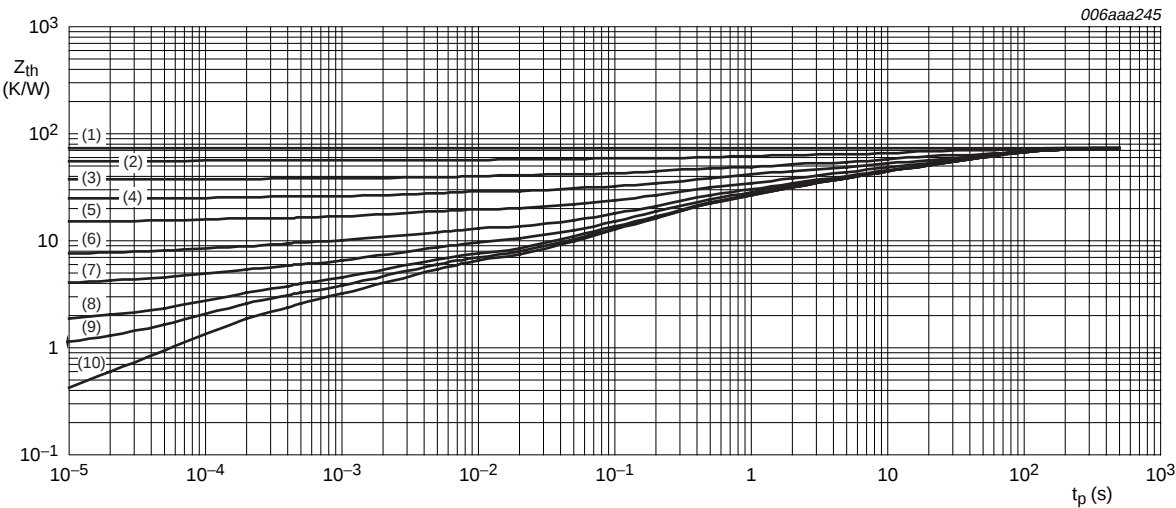
PBSS4350X



Mounted on FR4 printed-circuit board; mounting pad for collector 1 cm<sup>2</sup>.

- |                      |                      |                     |                      |                      |
|----------------------|----------------------|---------------------|----------------------|----------------------|
| (1) $\delta = 1.$    | (3) $\delta = 0.5.$  | (5) $\delta = 0.2.$ | (7) $\delta = 0.05.$ | (9) $\delta = 0.01.$ |
| (2) $\delta = 0.75.$ | (4) $\delta = 0.33.$ | (6) $\delta = 0.1.$ | (8) $\delta = 0.02.$ | (10) $\delta = 0.$   |

Fig.4 Transient thermal impedance as a function of pulse time; typical values.



Mounted on FR4 printed-circuit board; mounting pad for collector 6 cm<sup>2</sup>.

- |                      |                      |                     |                      |                      |
|----------------------|----------------------|---------------------|----------------------|----------------------|
| (1) $\delta = 1.$    | (3) $\delta = 0.5.$  | (5) $\delta = 0.2.$ | (7) $\delta = 0.05.$ | (9) $\delta = 0.01.$ |
| (2) $\delta = 0.75.$ | (4) $\delta = 0.33.$ | (6) $\delta = 0.1.$ | (8) $\delta = 0.02.$ | (10) $\delta = 0.$   |

Fig.5 Transient thermal impedance as a function of pulse time; typical values.

# 50 V, 3 A NPN low $V_{CEsat}$ (BISS) transistor

PBSS4350X

## CHARACTERISTICS

$T_{amb} = 25\text{ °C}$  unless otherwise specified.

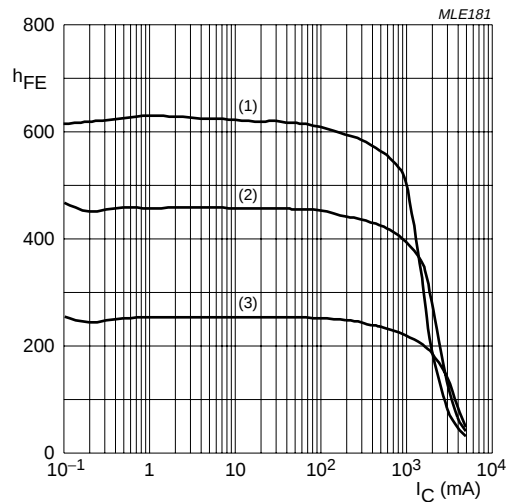
| SYMBOL      | PARAMETER                            | CONDITIONS                                                       | MIN. | TYP. | MAX. | UNIT             |
|-------------|--------------------------------------|------------------------------------------------------------------|------|------|------|------------------|
| $I_{CBO}$   | collector-base cut-off current       | $V_{CB} = 50\text{ V}; I_E = 0\text{ A}$                         | –    | –    | 100  | nA               |
|             |                                      | $V_{CB} = 50\text{ V}; I_E = 0\text{ A}; T_j = 150\text{ °C}$    | –    | –    | 50   | $\mu\text{A}$    |
| $I_{CES}$   | collector-emitter cut-off current    | $V_{CE} = 50\text{ V}; V_{BE} = 0\text{ V}$                      | –    | –    | 100  | nA               |
| $I_{EBO}$   | emitter-base cut-off current         | $V_{EB} = 5\text{ V}; I_C = 0\text{ A}$                          | –    | –    | 100  | nA               |
| $h_{FE}$    | DC current gain                      | $V_{CE} = 2\text{ V}$                                            |      |      |      |                  |
|             |                                      | $I_C = 0.1\text{ A}$                                             | 300  | –    | –    |                  |
|             |                                      | $I_C = 0.5\text{ A}$                                             | 300  | –    | –    |                  |
|             |                                      | $I_C = 1\text{ A}; \text{note 1}$                                | 300  | –    | 700  |                  |
|             |                                      | $I_C = 2\text{ A}; \text{note 1}$                                | 200  | –    | –    |                  |
|             |                                      | $I_C = 3\text{ A}; \text{note 1}$                                | 100  | –    | –    |                  |
| $V_{CEsat}$ | collector-emitter saturation voltage | $I_C = 0.5\text{ A}; I_B = 50\text{ mA}$                         | –    | –    | 80   | mV               |
|             |                                      | $I_C = 1\text{ A}; I_B = 50\text{ mA}$                           | –    | –    | 160  | mV               |
|             |                                      | $I_C = 2\text{ A}; I_B = 100\text{ mA}$                          | –    | –    | 280  | mV               |
|             |                                      | $I_C = 2\text{ A}; I_B = 200\text{ mA}; \text{note 1}$           | –    | –    | 260  | mV               |
|             |                                      | $I_C = 3\text{ A}; I_B = 300\text{ mA}; \text{note 1}$           | –    | –    | 370  | mV               |
| $R_{CEsat}$ | equivalent on-resistance             | $I_C = 2\text{ A}; I_B = 200\text{ mA}; \text{note 1}$           | –    | 100  | 130  | $\text{m}\Omega$ |
| $V_{BEsat}$ | base-emitter saturation voltage      | $I_C = 2\text{ A}; I_B = 100\text{ mA}$                          | –    | –    | 1.1  | V                |
|             |                                      | $I_C = 3\text{ A}; I_B = 300\text{ mA}; \text{note 1}$           | –    | –    | 1.2  | V                |
| $V_{BEon}$  | base-emitter turn-on voltage         | $V_{CE} = 2\text{ V}; I_C = 1\text{ A}$                          | 1.1  | –    | –    | V                |
| $f_T$       | transition frequency                 | $I_C = 100\text{ mA}; V_{CE} = 5\text{ V}; f = 100\text{ MHz}$   | 100  | –    | –    | MHz              |
| $C_c$       | collector capacitance                | $V_{CB} = 10\text{ V}; I_E = I_e = 0\text{ A}; f = 1\text{ MHz}$ | –    | –    | 25   | pF               |

### Note

1. Pulse test:  $t_p \leq 300\text{ }\mu\text{s}$ ;  $\delta \leq 0.02$ .

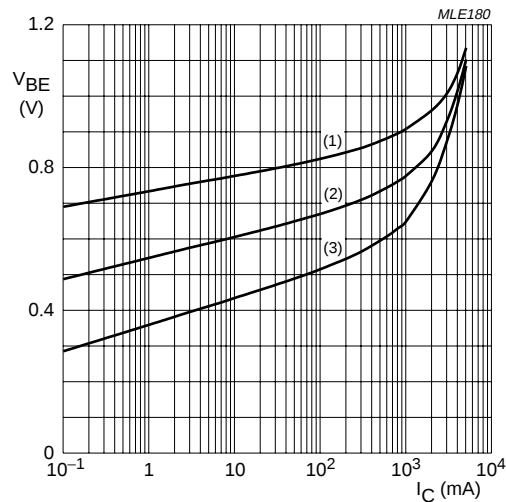
50 V, 3 A  
NPN low  $V_{CEsat}$  (BISS) transistor

PBSS4350X



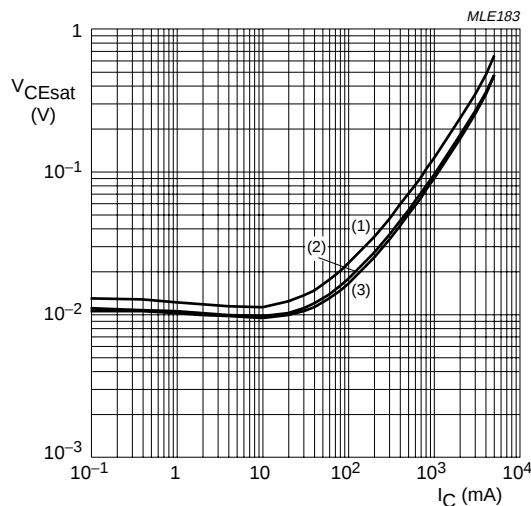
$V_{CE} = 2\text{ V}$ .  
(1)  $T_{amb} = 100^\circ\text{C}$ .  
(2)  $T_{amb} = 25^\circ\text{C}$ .  
(3)  $T_{amb} = -55^\circ\text{C}$ .

Fig.6 DC current gain as a function of collector current; typical values.



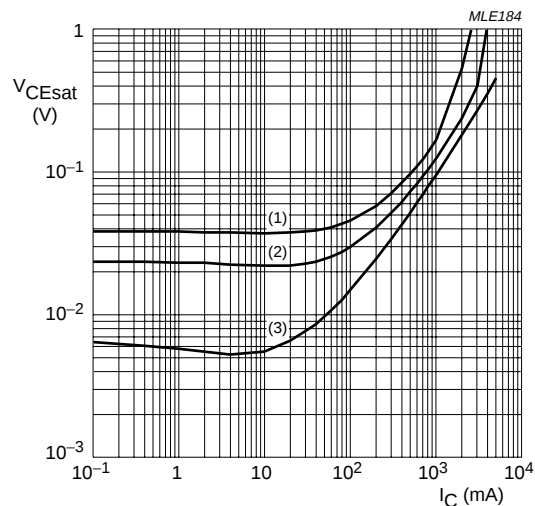
$V_{CE} = 2\text{ V}$ .  
(1)  $T_{amb} = -55^\circ\text{C}$ .  
(2)  $T_{amb} = 25^\circ\text{C}$ .  
(3)  $T_{amb} = 100^\circ\text{C}$ .

Fig.7 Base-emitter voltage as a function of collector current; typical values.



$I_C/I_B = 20$ .  
(1)  $T_{amb} = 100^\circ\text{C}$ .  
(2)  $T_{amb} = 25^\circ\text{C}$ .  
(3)  $T_{amb} = -55^\circ\text{C}$ .

Fig.8 Collector-emitter saturation voltage as a function of collector current; typical values.

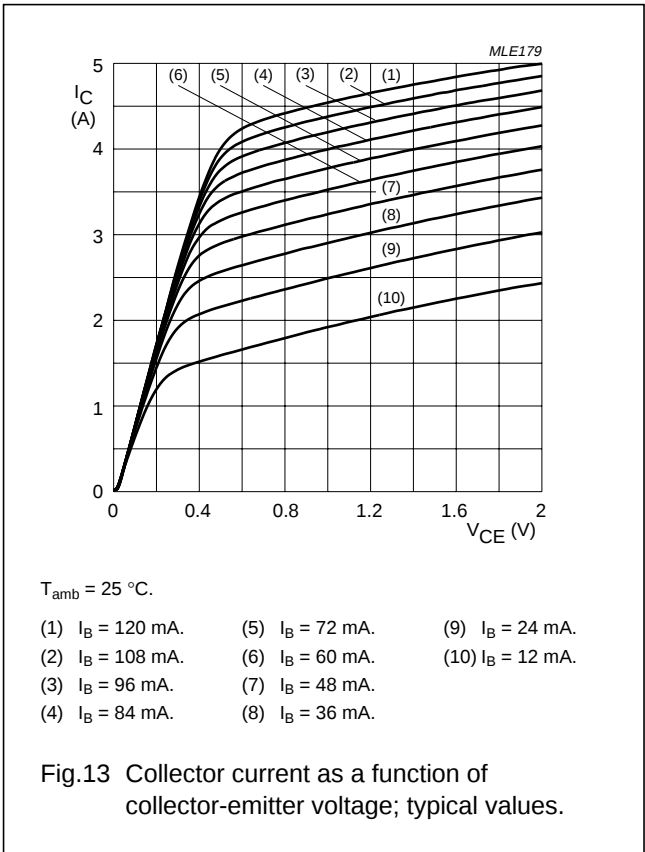
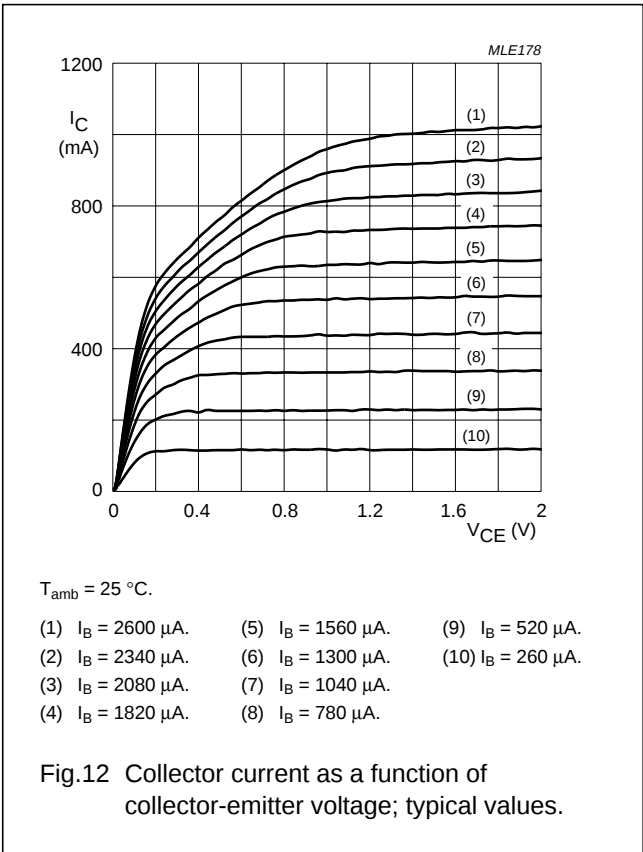
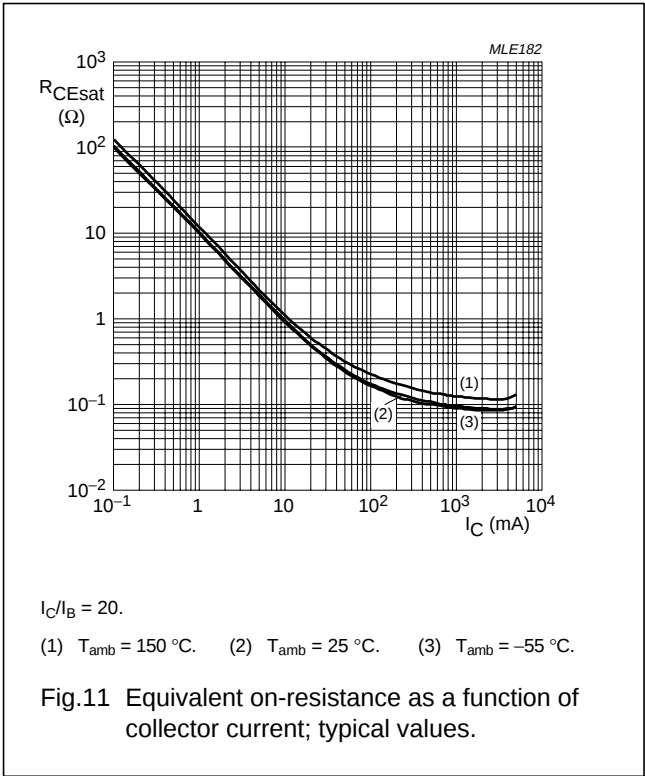
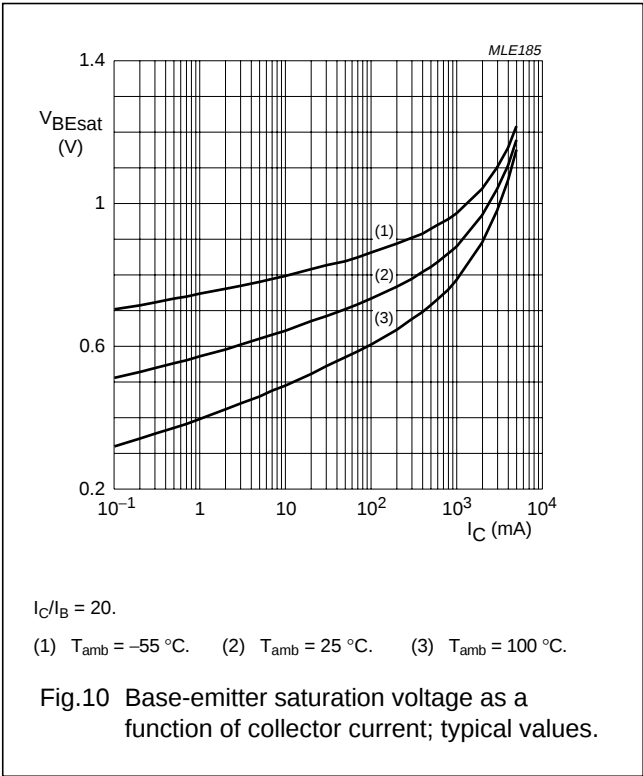


$T_{amb} = 25^\circ\text{C}$ .  
(1)  $I_C/I_B = 100$ .  
(2)  $I_C/I_B = 50$ .  
(3)  $I_C/I_B = 10$ .

Fig.9 Collector-emitter saturation voltage as a function of collector current; typical values.

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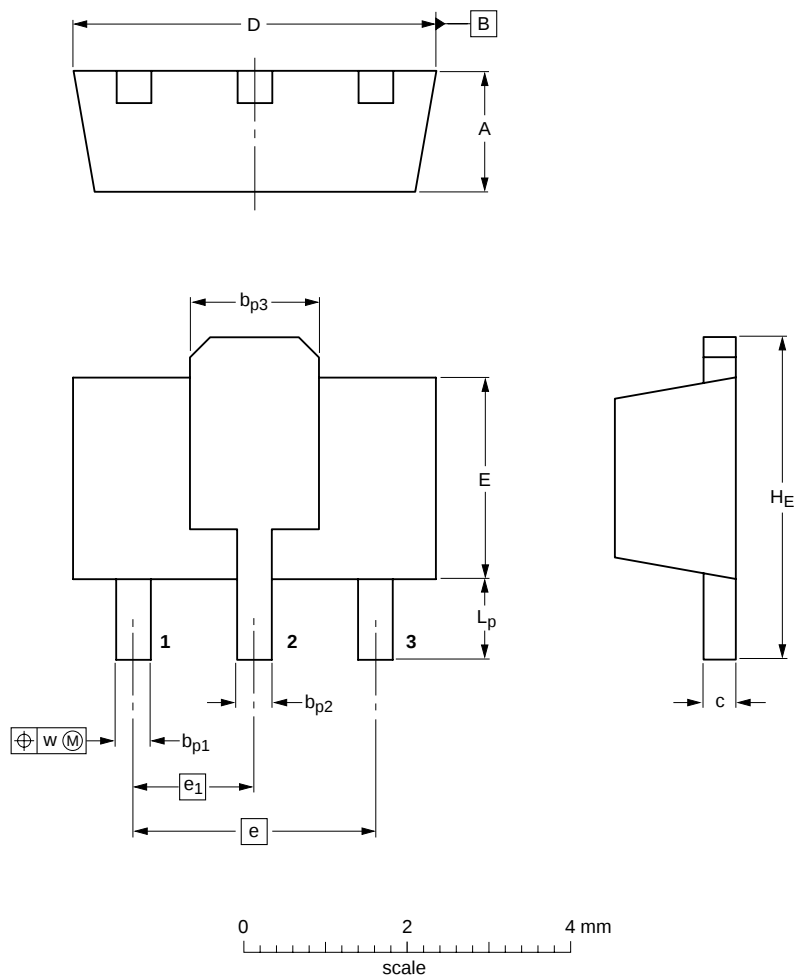
50 V, 3 A  
NPN low  $V_{CEsat}$  (BISS) transistor

PBSS4350X

PACKAGE OUTLINE

Plastic surface mounted package; collector pad for good heat transfer; 3 leads

SOT89



DIMENSIONS (mm are the original dimensions)

| UNIT | A          | b <sub>p1</sub> | b <sub>p2</sub> | b <sub>p3</sub> | c            | D          | E          | e   | e <sub>1</sub> | H <sub>E</sub> | L <sub>p</sub> | w    |
|------|------------|-----------------|-----------------|-----------------|--------------|------------|------------|-----|----------------|----------------|----------------|------|
| mm   | 1.6<br>1.4 | 0.48<br>0.35    | 0.53<br>0.40    | 1.8<br>1.4      | 0.44<br>0.23 | 4.6<br>4.4 | 2.6<br>2.4 | 3.0 | 1.5            | 4.25<br>3.75   | 1.2<br>0.8     | 0.13 |

| OUTLINE<br>VERSION | REFERENCES |        |       |  | EUROPEAN<br>PROJECTION                                                                | ISSUE DATE           |
|--------------------|------------|--------|-------|--|---------------------------------------------------------------------------------------|----------------------|
|                    | IEC        | JEDEC  | JEITA |  |                                                                                       |                      |
| SOT89              |            | TO-243 | SC-62 |  |  | 99-09-13<br>04-08-03 |

# 50 V, 3 A NPN low $V_{CEsat}$ (BISS) transistor

PBSS4350X

## DATA SHEET STATUS

| LEVEL | DATA SHEET STATUS <sup>(1)</sup> | PRODUCT STATUS <sup>(2)(3)</sup> | DEFINITION                                                                                                                                                                                                                                                                                     |
|-------|----------------------------------|----------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| I     | Objective data                   | Development                      | This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.                                                                                                    |
| II    | Preliminary data                 | Qualification                    | This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.             |
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Printed in The Netherlands

R75/03/pp12

Date of release: 2004 Nov 04

Document order number: 9397 750 13883

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